



**THE DATASHEET OF
MMB0207MC8203FB200**





Professional High Voltage Thin Film MELF Resistors



FEATURES

- High operating voltage, $U_{max.} = 1000\text{ V}$
- Advanced metal film technology
- Intrinsic sulfur resistance
- Excellent pulse load capability
- Material categorization:
for definitions of compliance please see www.vishay.com/doc?99912



LINKS TO ADDITIONAL RESOURCES



MMA 0204 HV and MMB 0207 HV professional thin film MELF resistors are the perfect choice for most fields of modern professional electronics where reliability and stability are of major concern. The devices' typical applications in the fields of lighting and medical equipment reflect the outstanding level of proven reliability.

APPLICATIONS

- Lighting
- Industrial
- Medical equipment

TECHNICAL SPECIFICATIONS		
DESCRIPTION	MMA 0204 HV	MMB 0207 HV
DIN size	0204	0207
Metric size code	RC3715M	RC6123M
Resistance range	340 kΩ to 10 MΩ	340 kΩ to 10 MΩ
Resistance tolerance	± 1 %	± 1 %
Temperature coefficient	± 50 ppm/K	± 50 ppm/K
Voltage coefficient c	< 2 ppm/V	< 2 ppm/V
Rated dissipation, $P_{70}^{(1)}$	0.4 W	1.0 W
Operating voltage, $U_{max. AC_{RMS}/DC}$	500 V	1000 V
Permissible film temperature, $\vartheta_{F max.}^{(1)}$	155 °C	
Operating temperature range ⁽¹⁾	-55 °C to 155 °C	
Permissible voltage against ambient (insulation): 1 min, U_{ins}	300 V	500 V
Internal thermal resistance (typical) ⁽¹⁾	46 K/W	26 K/W
Failure rate: FIT _{observed}	≤ 0.05 x 10 ⁻⁹ /h	

Note

(1) Please refer to APPLICATION INFORMATION below

APPLICATION INFORMATION

When the resistor dissipates power, a temperature rise above the ambient temperature occurs, dependent on the thermal resistance of the assembled resistor together with the printed circuit board. The rated dissipation applies only if the permitted film temperature is not exceeded.

Please consider the application note "Thermal Management in Surface-Mounted Resistor Applications" (www.vishay.com/doc?28844) for information on the general nature of thermal resistance.

These resistors do not feature a limited lifetime when operated within the permissible limits. However, resistance value drift increasing over operating time may result in exceeding a limit acceptable to the specific application, thereby establishing a functional lifetime.



MAXIMUM RESISTANCE CHANGE AT RATED DISSIPATION			
OPERATION MODE		STANDARD	POWER
Rated dissipation, P_{70}	MMA 0204 HV	0.25 W	0.4 W
	MMB 0207 HV	0.4 W	1.0 W
Operating temperature range		-55 °C to 125 °C	-55 °C to 155 °C
Permissible film temperature, ϑ_f max.		125 °C	155 °C
Max. resistance change at P_{70} for resistance range, $ \Delta R/R $ after:	MMA 0204 HV	340 k Ω to 10 M Ω	340 k Ω to 10 M Ω
	MMB 0207 HV	340 k Ω to 10 M Ω	340 k Ω to 10 M Ω
	1000 h	$\leq 0.25 \%$	$\leq 0.5 \%$
	8000 h	$\leq 0.5 \%$	$\leq 1 \%$
	225 000 h	$\leq 1.5 \%$	$\leq 3 \%$

Note

- The presented operation modes do not refer to different types of resistors, but actually show examples of different loads, that lead to different film temperatures and different achievable load-life stability (drift) of the resistance value. A suitable low thermal resistance of the circuit board assembly must be safeguarded in order to maintain the film temperature of the resistors within the specified limits. Please consider the application note "Thermal Management in Surface-Mounted Resistor Applications" (www.vishay.com/doc?28844) for information on the general nature of thermal resistance

TEMPERATURE COEFFICIENT AND RESISTANCE RANGE				
TYPE / SIZE	TCR	TOLERANCE	RESISTANCE	E-SERIES
MMA 0204 HV	± 50 ppm/K	$\pm 1 \%$	340 k Ω to 10 M Ω	E24; E96
MMB 0207 HV	± 50 ppm/K	$\pm 1 \%$	340 k Ω to 10 M Ω	E24; E96

PACKAGING						
TYPE / SIZE	CODE	QUANTITY	PACKAGING STYLE	WIDTH	PITCH	PACKAGING DIMENSIONS
MMA 0204 HV	B3 = BL	3000	Antistatic blister tape acc. IEC 60286-3, Type 2a	8 mm	4 mm	\varnothing 180 mm / 7"
	B0	10 000				\varnothing 330 mm / 13"
MMB 0207 HV	B2	2000		12 mm	4 mm	\varnothing 180 mm / 7"
	B7	7000				\varnothing 330 mm / 13"

PART NUMBER AND PRODUCT DESCRIPTION																	
Part Number: MMB0207MC3324FB200																	
M	M	B	0	2	0	7	M	C	3	3	2	4	F	B	2	0	0
TYPE/SIZE		VERSION		TCR		RESISTANCE			TOLERANCE		PACKAGING						
MMA0204 MMB0207		M = HV		C = ± 50 ppm/K		3 digit value 1 digit multiplier Multiplier 3 = $\cdot 10^3$ 4 = $\cdot 10^4$ 5 = $\cdot 10^5$			F = $\pm 1 \%$		B3 B0 B2 B7						
Product Description: MMB 0207 -50 1 % HV B2 3M32																	
MMB	0207	-50	1 %	HV	B2	3M32											
TYPE	SIZE	TCR	TOLERANCE	VERSION	PACKAGING	RESISTANCE											
MMA MMB	0204 0207	± 50 ppm/K	$\pm 1 \%$	HV = high voltage	BL B0 B2 B7	3M32 = 3.32 M Ω											

Note

- Products can be ordered using either the PART NUMBER or the PRODUCT DESCRIPTION



DESCRIPTION

Production is strictly controlled and follows an extensive set of instructions established for reproducibility. A homogeneous film of metal alloy is deposited on a high grade ceramic body (Al₂O₃) and conditioned to achieve the desired temperature coefficient. Nickel plated steel termination caps are firmly pressed on the metallised rods. A special laser is used to achieve the target value by smoothly cutting a helical groove in the resistive layer without damaging the ceramics. The resistor elements are covered by a protective coating designed for electrical, mechanical and climatic protection. The terminations receive a final pure matte tin on nickel plating. Four or five color code rings designate the resistance value and tolerance in accordance with **IEC 60062** ⁽¹⁾.

The result of the determined production is verified by an extensive testing procedure performed on 100 % of the individual resistors. This includes full screening for the elimination of products with a potential risk of early field failures according to EN 140401-803, 2.1.2.2. Only accepted products are laid directly into the blister tape in accordance with **IEC 60286-3, Type 2a** ⁽¹⁾.

ASSEMBLY

The resistors are suitable for processing on automatic SMD assembly systems. They are suitable for automatic soldering using wave, reflow or vapor phase as shown in **IEC 61760-1** ⁽¹⁾. The encapsulation is resistant to all cleaning solvents commonly used in the electronics industry, including alcohols, esters and aqueous solutions. The suitability of conformal coatings, potting compounds and their processes, if applied, shall be qualified by appropriate means to ensure the long term stability of the whole system. The resistors are completely lead (Pb)-free, the pure matte tin plating provides compatibility with lead (Pb)-free and lead containing soldering processes. Solderability is specified for 2 years after production or requalification, however, excellent solderability is proven after extended storage in excess of 10 years. The permitted storage time is 20 years. The immunity of the plating against tin whisker growth has been proven under extensive testing.

Notes

- ⁽¹⁾ The quoted IEC standards are also released as EN standards with the same number and identical contents
- ⁽²⁾ The IEC 62474 list of declarable substances is maintained in a dedicated database, which is available at <http://std.iec.ch/iec62474>.
- ⁽³⁾ The Global Automotive Declarable Substance List (GADSL) is maintained by the American Chemistry Council and available at www.gadsl.org
- ⁽⁴⁾ The SVHC list is maintained by the European Chemical Agency (ECHA) and available at <http://echa.europa.eu/candidate-list-table>

MATERIALS

Vishay acknowledges the following systems for the regulation of hazardous substances:

- IEC 62474, Material Declaration for Products of and for the Electrotechnical Industry, with the list of declarable substances given therein ⁽²⁾
- The Global Automotive Declarable Substance List (GADSL) ⁽³⁾
- The REACH regulation (1907/2006/EC) and the related list of substances with very high concern (SVHC) ⁽⁴⁾ for its supply chain

The products do not contain any of the banned substances as per IEC 62474, GADSL, or the SVHC list, see www.vishay.com/how/leadfree.

Hence the products fully comply with the following directives:

- 2000/53/EC End-of-Life Vehicle Directive (ELV) and Annex II (ELV II)
- 2011/65/EU Restriction of the Use of Hazardous Substances Directive (RoHS) with amendment 2015/863/EU
- 2012/19/EU Waste Electrical and Electronic Equipment Directive (WEEE)

Vishay pursues the elimination of conflict minerals from its supply chain, see the Conflict Minerals Policy at www.vishay.com/doc?49037.

APPROVALS

Where applicable, the resistors are tested in accordance with **EN 140401-803** which refers to **EN 60115-1, EN 60115-8** and the variety of environmental test procedures of the **IEC 60068** ⁽¹⁾ series.

Vishay Beyschlag has achieved **“Approval of Manufacturer”** in accordance with **IECQ 03-1**. The release certificate for **“Technology Approval Schedule”** in accordance with **CECC 240001** based on **IECQ 03-3-1** is granted for the Vishay Beyschlag manufacturing process.

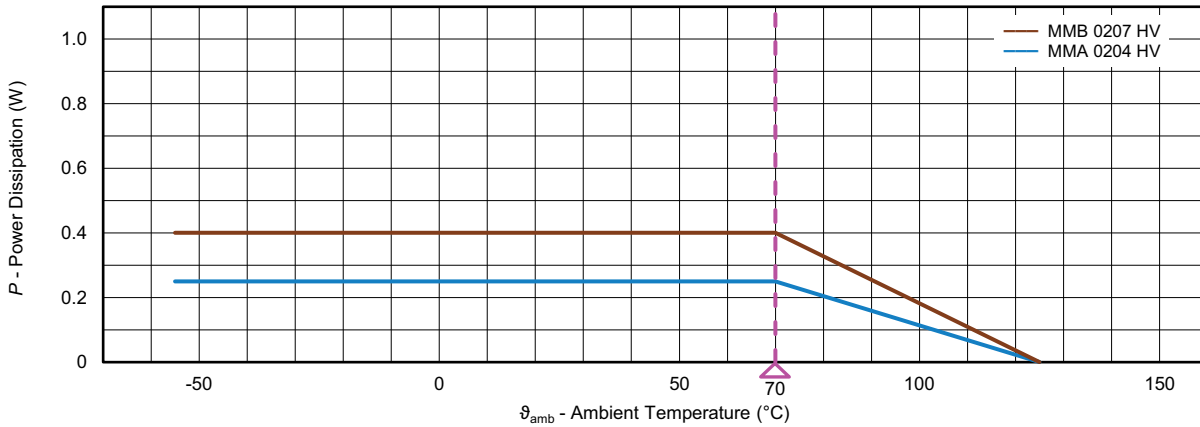
RELATED PRODUCTS

For products with professional specification see the datasheet:

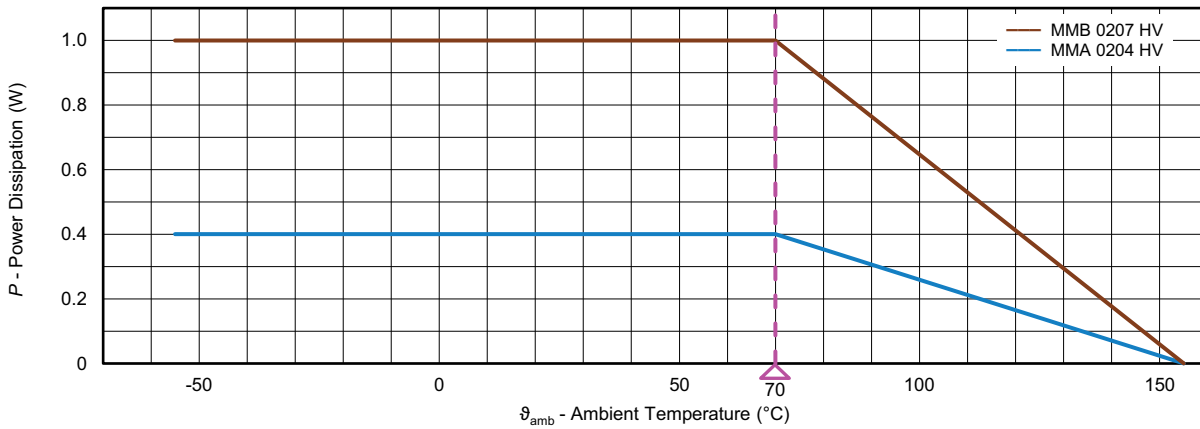
- “Professional Thin Film MELF Resistors”
www.vishay.com/doc?28713
- “Precision High Voltage Thin Film MELF Resistors”
www.vishay.com/doc?28951



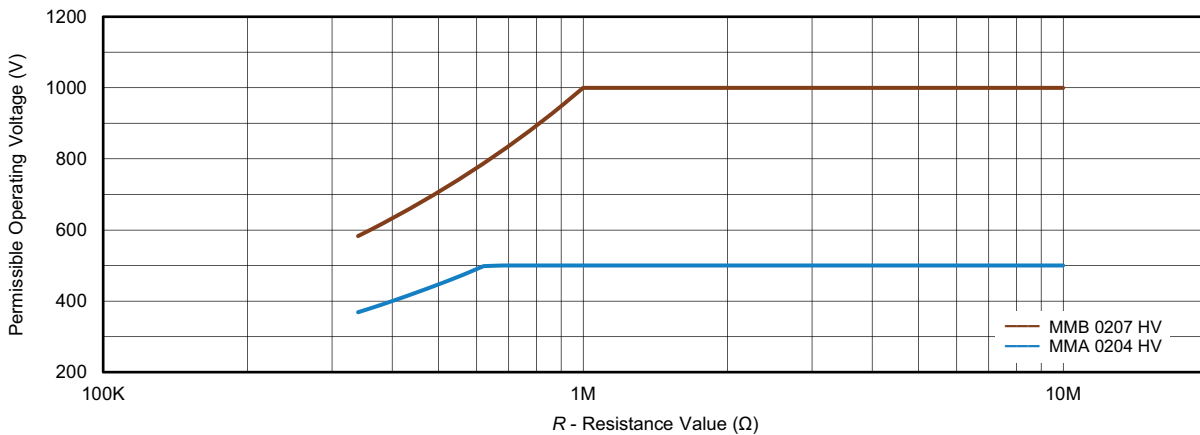
FUNCTIONAL PERFORMANCE



Derating - Standard Operation Mode

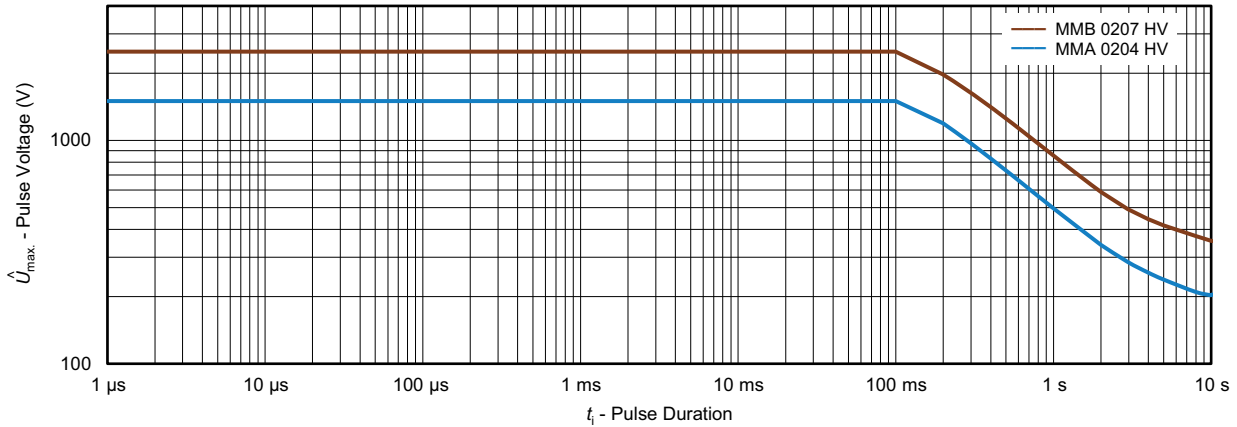


Derating - Power Operation Mode



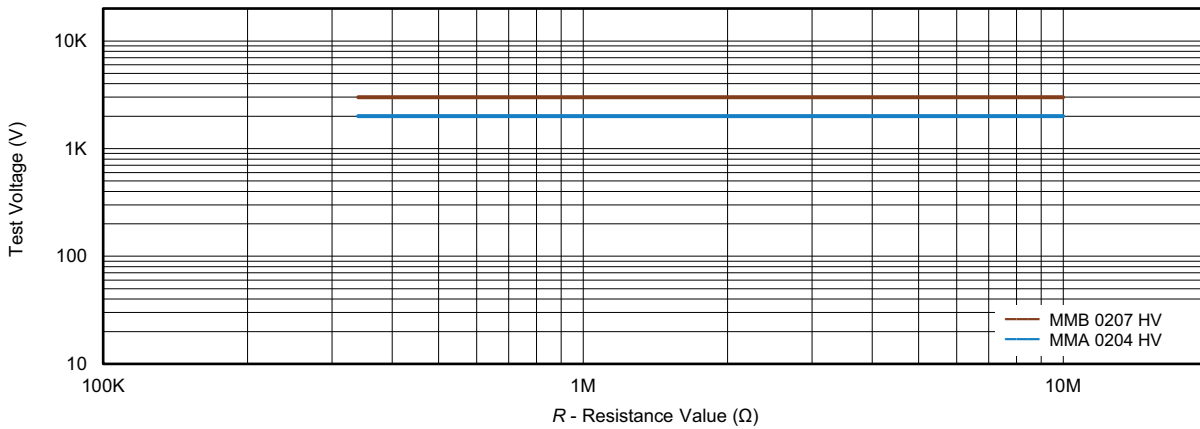
The permissible operating voltage equals the rated voltage $U_R = \sqrt{P_{T0} \times R}$.
 For ambient temperatures above 70 °C power derating must be considered

Nominal Operating Voltage



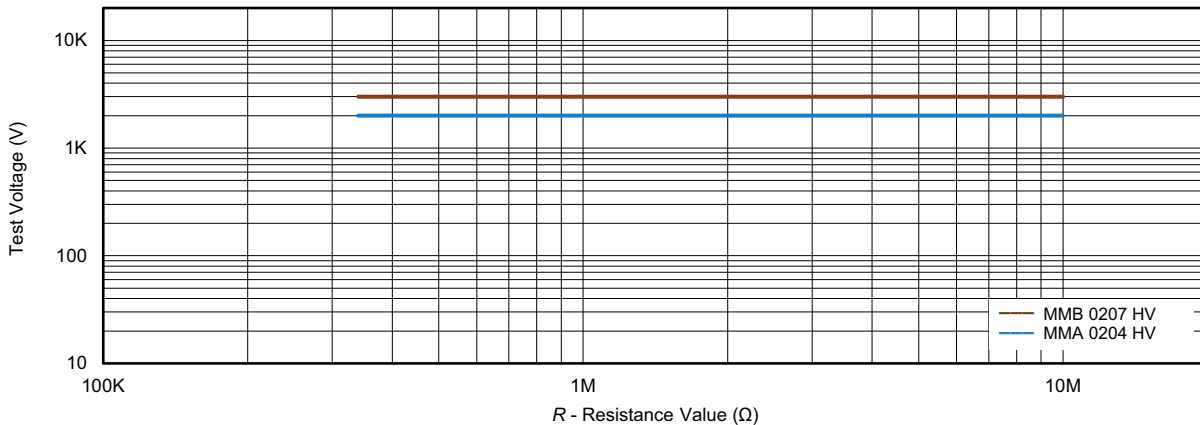
Maximum pulse voltage, single and continuous pulses; applicable if $\hat{P} \leq \hat{P}_{max}$; for permissible resistance change $\pm (0.5\% R + 0.01 \Omega)$

Pulse Voltage



Pulse load rating in accordance with IEC 60115-1, 4.27; 1.2 μs/50 μs; 5 pulses at 12 s intervals; for permissible resistance change $\pm (0.5\% R + 0.05 \Omega)$

1.2/50 Pulse



Pulse load rating in accordance with IEC 60115-1, 4.27; 10 μs/700 μs; 10 pulses at 1 minute intervals; for permissible resistance change $\pm (0.5\% R + 0.05 \Omega)$

10/700 Pulse



TESTS AND REQUIREMENTS

All tests are carried out in accordance with the following specifications:

- EN 60115-1, generic specification
- EN 60115-8, sectional specification
- EN 140401-803, detail specification
- IEC 60068-2-xx, test methods

The parameters stated in the Test Procedures and Requirements table are based on the required tests and permitted limits of EN 140401-803. The table presents only the most important tests, for the full test schedule refer to the documents listed above. However, some additional tests and a number of improvements against those minimum requirements have been included.

The testing also covers most of the requirements specified by EIA/ECA-703 and JIS-C-5201-1.

The tests are carried out under standard atmospheric conditions in accordance with IEC 60068-1, 4.3, whereupon the following values are applied:

- Temperature: 15 °C to 35 °C
- Relative humidity: 25 % to 75 %
- Air pressure: 86 kPa to 106 kPa (860 mbar to 1060 mbar).

A climatic category LCT/UCT/56 is applied, defined by the lower category temperature (LCT), the upper category temperature (UCT), and the duration of exposure in the damp heat, steady state test (56 days).

The components are mounted for testing on printed circuit boards in accordance with EN 60115-8, 2.4.2, unless otherwise specified.

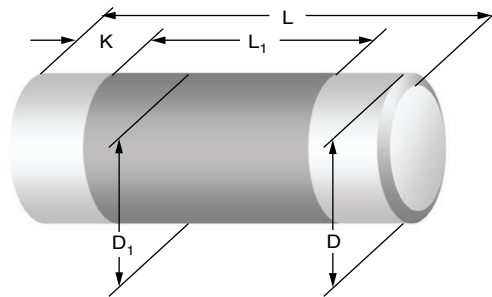
TEST PROCEDURES AND REQUIREMENTS					
EN 60115-1 CLAUSE	IEC 60068-2 ⁽¹⁾ TEST METHOD	TEST	PROCEDURE	REQUIREMENTS PERMISSIBLE CHANGE (ΔR)	
			Stability for product types:	STABILITY CLASS 0.25 OR BETTER	STABILITY CLASS 2 OR BETTER
			MMA 0204 HV	-	> 340 k Ω
			MMB 0207 HV	340 k Ω to 1 M Ω	> 1 M Ω
4.5	-	Resistance	-	$\pm 1 \% R$	$\pm 1 \% R$
4.8	-	Temperature coefficient	At (20/-55/20) °C and (20/125/20) °C	± 50 ppm/K	
4.25.1	-	Endurance at 70 °C: Standard operation mode	$U = \sqrt{P_{70} \times R}$ or $U = U_{max.}$; whichever is the less severe; 1.5 h on; 0.5 h off; 70 °C; 1000 h 70 °C; 8000 h	$\pm (0.15 \% R + 10 \text{ m}\Omega)$ $\pm (0.3 \% R + 10 \text{ m}\Omega)$	$\pm (0.25 \% R + 10 \text{ m}\Omega)$ $\pm (0.5 \% R + 10 \text{ m}\Omega)$
	-	Endurance at 70 °C: Power operation mode	$U = \sqrt{P_{70} \times R}$ or $U = U_{max.}$; whichever is the less severe; 1.5 h on; 0.5 h off; 70 °C; 1000 h 70 °C; 8000 h	$\pm (0.3 \% R + 10 \text{ m}\Omega)$ $\pm (1 \% R + 10 \text{ m}\Omega)$	$\pm (0.5 \% R + 10 \text{ m}\Omega)$ $\pm (1 \% R + 10 \text{ m}\Omega)$
4.25.3	-	Endurance at upper category temperature	125 °C; 1000 h	$\pm (0.15 \% R + 5 \text{ m}\Omega)$	$\pm (0.25 \% R + 5 \text{ m}\Omega)$
			155 °C; 1000 h	$\pm (0.3 \% R + 5 \text{ m}\Omega)$	$\pm (0.5 \% R + 5 \text{ m}\Omega)$
4.24	78 (Cab)	Damp heat, steady state	(40 \pm 2) °C; 56 days; (93 \pm 3) % RH	$\pm (0.15 \% R + 10 \text{ m}\Omega)$	$\pm (0.25 \% R + 10 \text{ m}\Omega)$
-	1 (Ab)	Cold	-55 °C; 2 h	$\pm (0.05 \% R + 5 \text{ m}\Omega)$	$\pm (0.1 \% R + 5 \text{ m}\Omega)$
4.19	14 (Na)	Rapid change of temperature	30 min at LCT; 30 min at UCT; LCT = -55 °C; UCT = 155 °C 1000 cycles	$\pm (0.25 \% R + 10 \text{ m}\Omega)$	$\pm (0.5 \% R + 10 \text{ m}\Omega)$



TEST PROCEDURES AND REQUIREMENTS					
EN 60115-1 CLAUSE	IEC 60068-2 ⁽¹⁾ TEST METHOD	TEST	PROCEDURE	REQUIREMENTS PERMISSIBLE CHANGE (ΔR)	
			Stability for product types:	STABILITY CLASS 0.25 OR BETTER	STABILITY CLASS 2 OR BETTER
			MMA 0204 HV	-	> 340 k Ω
			MMB 0207 HV	340 k Ω to 1 M Ω	> 1 M Ω
4.13	-	Short time overload: Standard operation mode	$U = 2.5 \times \sqrt{P_{70} \times R}$ or $U = 2 \times U_{max.}$; whichever is the less severe; 5 s	$\pm (0.03 \% R + 5 \text{ m}\Omega)$	$\pm (0.15 \% R + 5 \text{ m}\Omega)$
		Short time overload: Power operation mode		$\pm (0.05 \% R + 5 \text{ m}\Omega)$	$\pm (0.15 \% R + 5 \text{ m}\Omega)$
4.22	6 (Fc)	Vibration	Endurance by sweeping; 10 Hz to 2000 Hz; no resonance; amplitude $\leq 1.5 \text{ mm}$ or $\leq 200 \text{ m/s}^2$; 7.5 h	$\pm (0.05 \% R + 5 \text{ m}\Omega)$	$\pm (0.1 \% R + 5 \text{ m}\Omega)$
4.38	-	Electrostatic discharge (Human Body Model)	IEC 61340-3-1 ⁽¹⁾ ; 3 pos. + 3 neg. discharges MMA 0204 HV: 2 kV MMB 0207 HV: 4 kV	$\pm (0.5 \% R + 50 \text{ m}\Omega)$	
4.17	58 (Td)	Solderability	Solder bath method; SnPb40; non-activated flux; (215 \pm 3) °C; (3 \pm 0.3) s	Good tinning ($\geq 95 \%$ covered); no visible damage	
			Solder bath method; SnAg3Cu0.5 or SnAg3.5; non-activated flux; (235 \pm 3) °C; (2 \pm 0.2) s	Good tinning ($\geq 95 \%$ covered); no visible damage	
4.18	58 (Td)	Resistance to soldering heat	Solder bath method; (260 \pm 5) °C; (10 \pm 1) s	$\pm (0.05 \% R + 10 \text{ m}\Omega)$	$\pm (0.25 \% R + 10 \text{ m}\Omega)$
			Reflow method 2 (IR/forced gas convection); (260 \pm 5) °C; (10 \pm 1) s	$\pm (0.02 \% R + 10 \text{ m}\Omega)$	$\pm (0.1 \% R + 10 \text{ m}\Omega)$
4.29	45 (XA)	Component solvent resistance	Isopropyl alcohol; 50 °C; method 2	No visible damage	
4.30	45 (XA)	Solvent resistance of marking	Isopropyl alcohol; 50 °C; method 1, toothbrush	Marking legible; no visible damage	
4.32	21 (Ue ₃)	Shear (adhesion)	45 N	No visible damage	
4.33	21 (Ue ₁)	Substrate bending	Depth 2 mm, 3 times	No visible damage, no open circuit in bent position $\pm (0.05 \% R + 10 \text{ m}\Omega)$	
4.7	-	Voltage proof	$U_{RMS} = U_{ins}$; 60 s	No flashover or breakdown	
4.35	-	Flammability	IEC 60695-11-5 ⁽¹⁾ , needle flame test; 10 s	No burning after 30 s	

Note

⁽¹⁾ The quoted IEC standards are also released as EN standards with the same number and identical contents

DIMENSIONS


DIMENSIONS AND MASS						
TYPE / SIZE	L (mm)	D (mm)	L ₁ min. (mm)	D ₁ (mm)	K (mm)	MASS (mg)
MMA 0204 HV	3.6 + 0/- 0.2	1.4 + 0/- 0.1	1.8	D + 0/- 0.15	0.75 ± 0.1	22
MMB 0207 HV	5.8 + 0/- 0.15	2.2 + 0/- 0.2	3.2	D + 0/- 0.2	1.15 ± 0.1	80

Notes

- Color code marking is applied according to IEC 60062 ⁽¹⁾ in four bands (E24 series) or five bands (E96 series). Each color band appears as a single solid line, voids are permissible if at least 2/3 of the band is visible from each radial angle of view. The last color band for tolerance is approximately 50 % wider than the other bands. An interrupted violet band between the 3rd and 4th full band identifies the special high voltage type
- ⁽¹⁾ The quoted IEC standards are also released as EN standards with the same number and identical contents.

SOLDERING RECOMMENDATIONS

For recommended solder pad dimensions please refer to www.vishay.com/doc?28950.

For recommended soldering profiles please refer to www.vishay.com/doc?31090.



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